

Bondline™ 2013 is an electrically conductive semiconductor grade adhesive. This stress absorbing, silver filled epoxy is designed for bonding chips to substrates with a mismatch in coefficient of thermal expansion.

*“A Reliable
and Responsive
Adhesive
Company.”*

Adhesive Properties

Color:	Silver
Viscosity*:	43,000 cps
Work Life @ 25°C:	8 hours
Hardness (Shore A):	65
Cure Options:	1 hour @ 125°C 3 hours @ 100° 6 hours @ 75°
Service Temperature Range:	-55°C to 125°C
Lap Shear Strength @ 25°C (Al to Al) :	300 psi
@ 25°C (Au/Au) :	500 psi
Specific Gravity:	3.9
Bond Joint Resistance (Au/Au):	.00002 ohm
Glass Transition Temperature (Tg)**:	-50°C
Shelf Life:	1 Year
Storage:	Store at -40°C or Colder
Availability:	Net volume 1cc to 5cc, available in disposable 3cc & 5cc syringes.

Adhesive properties are not intended to be used as specification limits.

* Brookfield DV11+, Spindle CP 51, 5 rpm, 25°C

** Cured 1hours @ 125°C

Bondline™

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